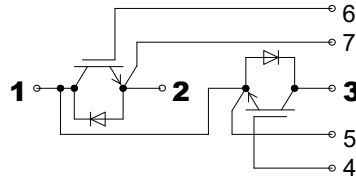


SGG400T60UC2

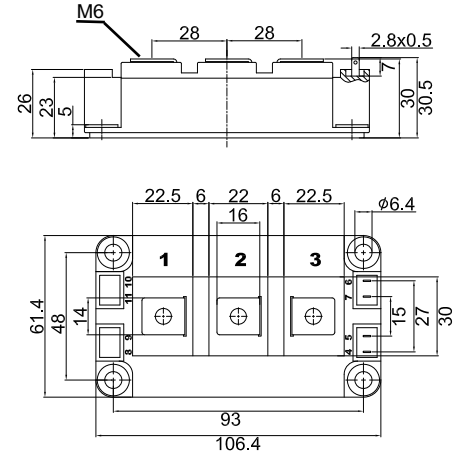
IGBT Modules



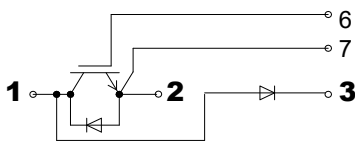
**SGG400T60UC2
(Half Bridge)**



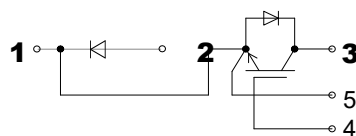
Dimensions in mm (1mm = 0.0394")



**SGD400T60UC2
(Boost Chopper)**



**SDG400T60UC2
(Buck Chopper)**



$T_C = 25^\circ\text{C}$, unless otherwise specified

Symbol	Conditions	Values	Units
IGBT			
V_{CES}		600	V
I_C	$T_C = 25(100)^\circ\text{C}$	800(400)	A
I_{CRM}	$T_C = 25^\circ\text{C}$, $t_P = 1\text{ms}$	800	A
V_{GES}		± 20	V
T_{Vj}		$-40 \dots +175$	$^\circ\text{C}$
Inverse Diode			
$I_F = -I_C$	$T_C = 25(80)^\circ\text{C}$	800(400)	A
I_{FRM}	$T_C = 25^\circ\text{C}$, $t_P = 1\text{ms}$	800	A
I_{FSM}	$t_P = 10\text{ms}$; $\sin 180^\circ$; $T_j = 25^\circ\text{C}$	800	A
V_{RRM}		600	V
Module			
$I_{t(RMS)}$	$T_{terminal} = 80^\circ\text{C}$	400	A
T_{stg}		$-40 \sim 125$	$^\circ\text{C}$
V_{isol}	AC, 1min	2500	V

Features

- Trench FS IGBT technology
- Low switching losses
- Switching frequency up to 30kHz
- Square RBSOA, no latch up
- High short circuit capability
- Positive temperature coefficient for easy paralleling
- MOS input, voltage controlled
- Soft switching FWD diode Technology
- Package with copper baseplate
- Isolation voltage 2500 V

Application

- Inverter welding Machines
- UPS systems
- Power converters

Advantages

- space and weight savings
- reduced protection circuits



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IGBT Modules

Characteristics

$T_C = 25^{\circ}\text{C}$, unless otherwise specified

Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 3\text{mA}$	4.5	5.0	6.0	V
I_{CES}	$V_{GE} = 0$; $V_{CE} = V_{CES}$; $T_J = 25^{\circ}\text{C}$			0.10	mA
$V_{CE(TO)}$	$T_J = 25^{\circ}\text{C}$		0.9	1.0	V
r_{CE}	$V_{GE} = 15\text{V}$, $T_J = 25(150)^{\circ}\text{C}$		1.4(0.8)	2.4(0.9)	$\text{m}\Omega$
$V_{CE(sat)}$	$I_C = 400\text{A}$; $V_{GE} = 15\text{V}$; chip level		1.65	2.10	V
C_{ies}	under following conditions $V_{GE} = 0$, $V_{CE} = 25\text{V}$, $f = 1\text{MHz}$		25		nF
C_{oes}			0.96		
C_{res}			0.75		
L_{CE}				30	nH
$R_{CC'+EE'}$	res., terminal-chip $T_C = 25(125)^{\circ}\text{C}$		0.65(1.09)		$\text{m}\Omega$
$t_{d(on)}$	under following conditions: $V_{CC} = 300\text{V}$, $I_C = 400\text{A}$ $R_{Gon} = R_{Goff} = 1\Omega$, $T_J = 150^{\circ}\text{C}$ $V_{GE} = \pm 15\text{V}$		108		ns
t_r			52		ns
$t_{d(off)}$			450		ns
t_f			69		ns
$E_{on}/E_{off}/E_{ts}$			2.2/16.4/18.6		mJ
Inverse Diode under following conditions: $I_F = 400\text{A}$;					
$V_F = V_{EC}$	$V_{GE} = 0\text{V}$; $T_J = 25^{\circ}\text{C}$		1.55		V
$V_{(FO)}$	$T_J = 25(125)^{\circ}\text{C}$		0.9(0.80)	1.1(1.0)	V
r_F	$T_J = 25(125)^{\circ}\text{C}$		1.7(2.4)	2.1(2.7)	$\text{m}\Omega$
I_{RM}	$I_F = 300\text{A}$; $T_J = 125^{\circ}\text{C}$		216		A
Q_{rr}	$di/dt = 100\text{A}/\mu\text{s}$		15		μC
E_{rr}	$V_{GE} = \pm 15\text{V}$		4.8		mJ
Thermal Characteristics					
$R_{th(j-c)}$	per IGBT			0.12	K/W
$R_{th(j-c)D}$	per Inverse Diode			0.22	K/W
$R_{th(c-s)}$	per module			0.08	K/W
Mechanical Data					
M_s	to heatsink M6	3		5	Nm
M_t	to terminals M6	2.5		5	Nm
Weight	typical			325	g

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Fig.1 Output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$

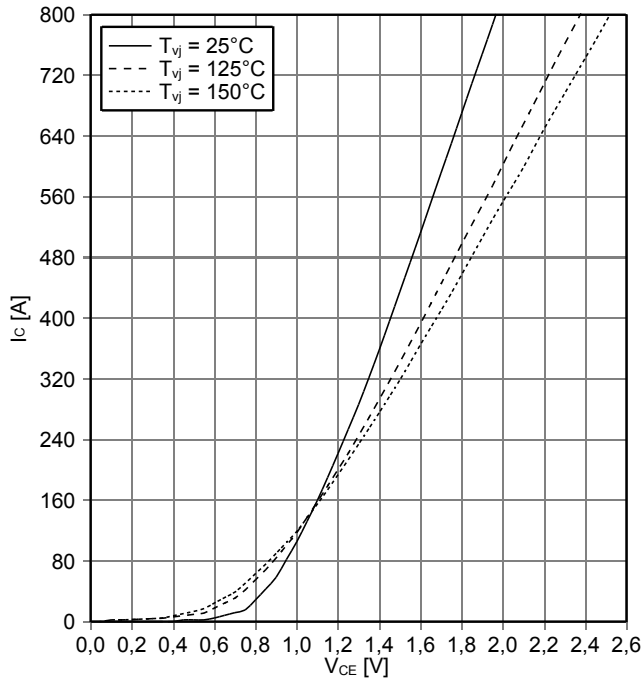


Fig.2 Output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$

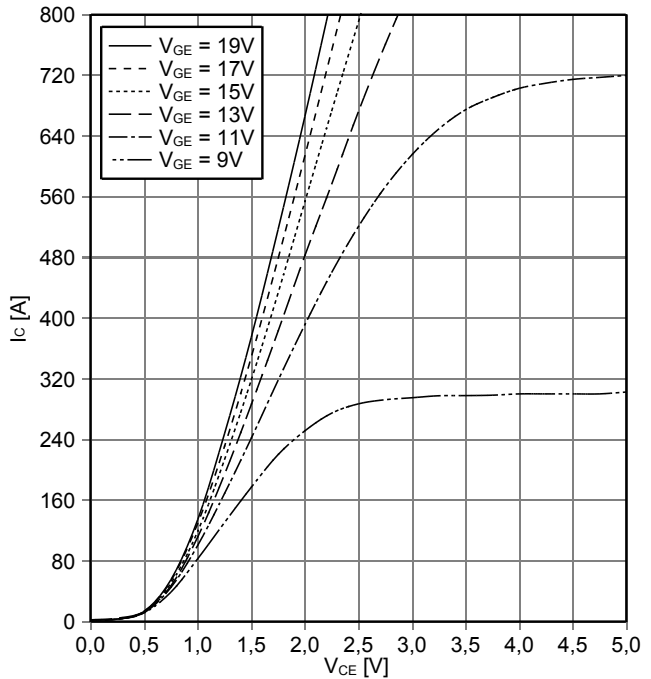


Fig.3 Transfer characteristic IGBT, Inverter (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$

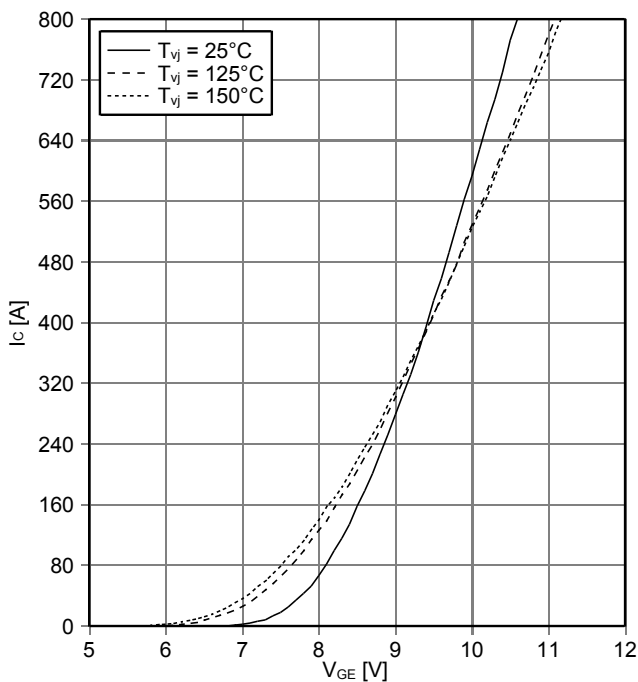
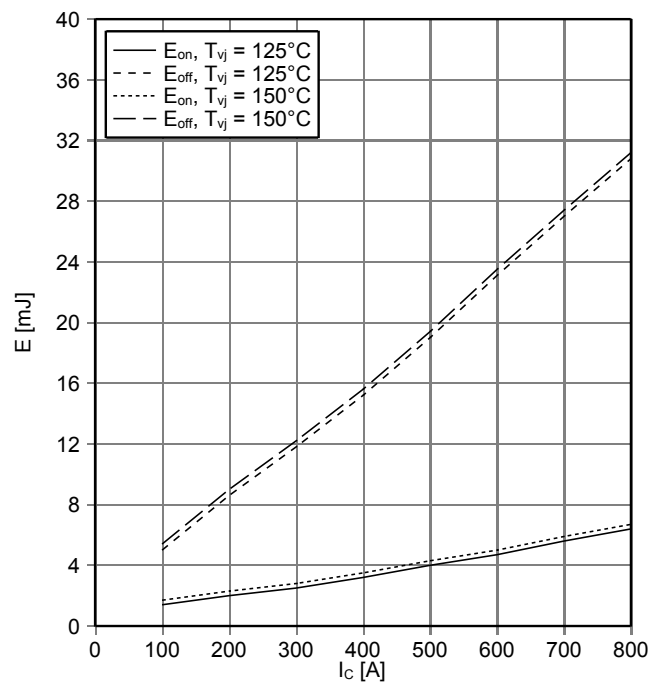


Fig.4 Switching losses IGBT, Inverter (typical)

$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 2.4\ \Omega$, $R_{Goff} = 2.4\ \Omega$, $V_{CE} = 300\text{ V}$



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Fig.5 Switching losses IGBT, Inverter (typical)

$E_{on} = f(R_G)$, $E_{off} = f(R_G)$

$V_{GE} = \pm 15 \text{ V}$, $I_C = 300 \text{ A}$, $V_{CE} = 300 \text{ V}$

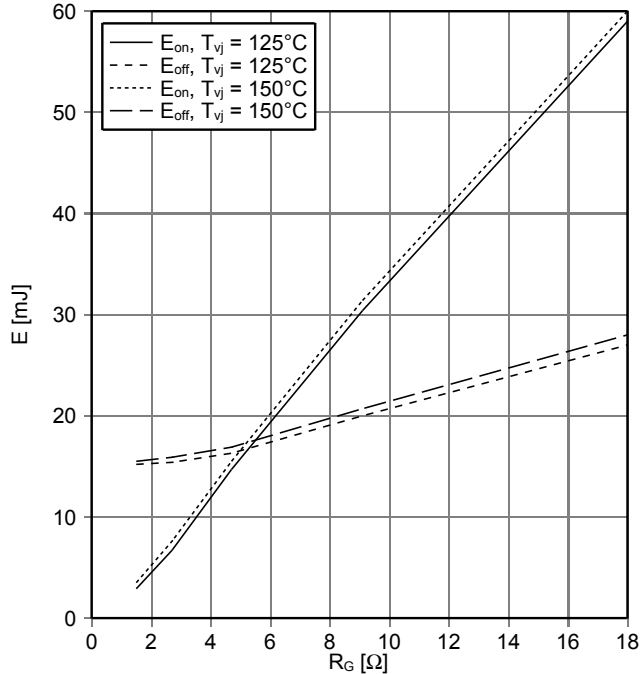


Fig.6 Transient thermal impedance IGBT, Inverter

$Z_{thJC} = f(t)$

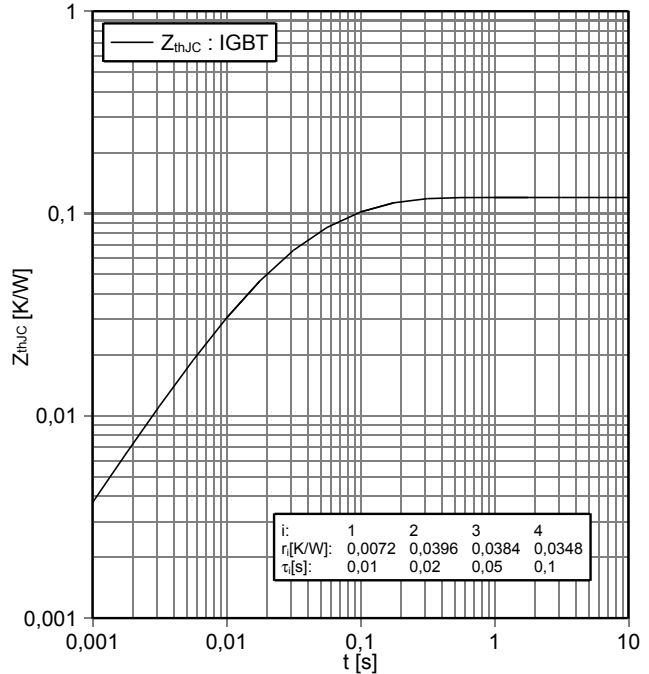


Fig.7 Reverse bias safe operating area IGBT, Inverter (RBSOA)

$I_C = f(V_{CE})$

$V_{GE} = \pm 15 \text{ V}$, $R_{Goff} = 2.4 \Omega$, $T_{vj} = 150^\circ\text{C}$

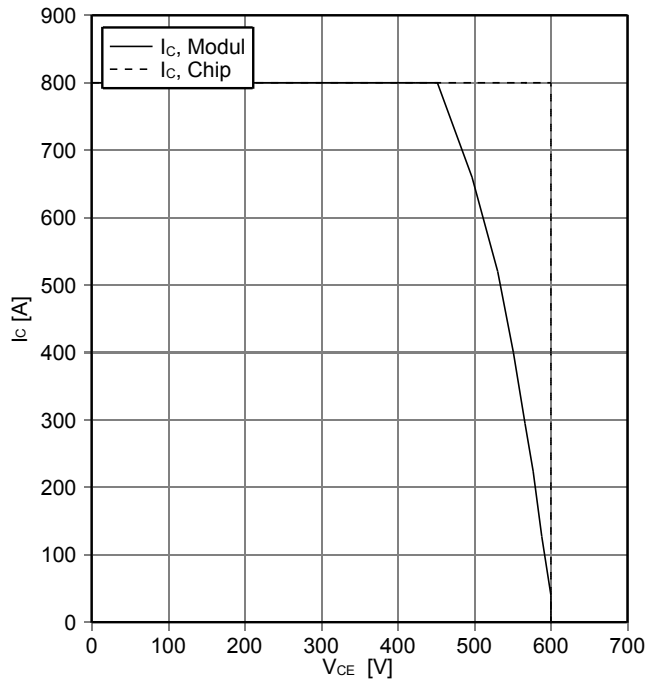
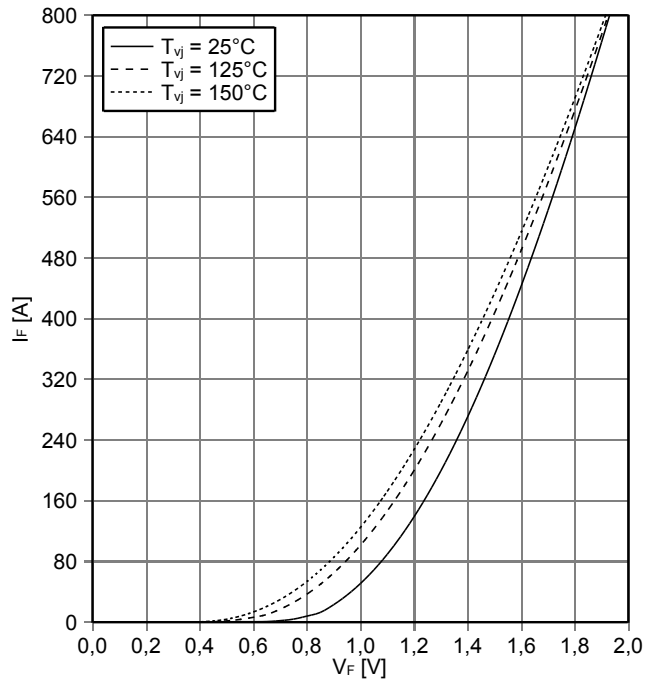


Fig.8 Forward characteristic of Diode, Inverter (typical)

$I_F = f(V_F)$



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Fig.9 Switching losses Diode, Inverter (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 2.4 \Omega$, $V_{CE} = 300 V$

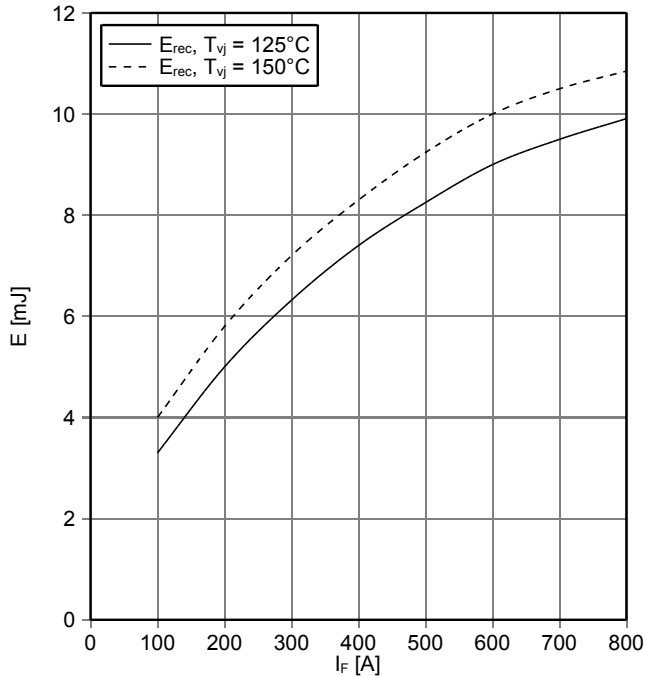


Fig.10 Switching losses Diode, Inverter (typical)

$E_{rec} = f(R_G)$
 $I_F = 300 A$, $V_{CE} = 300 V$

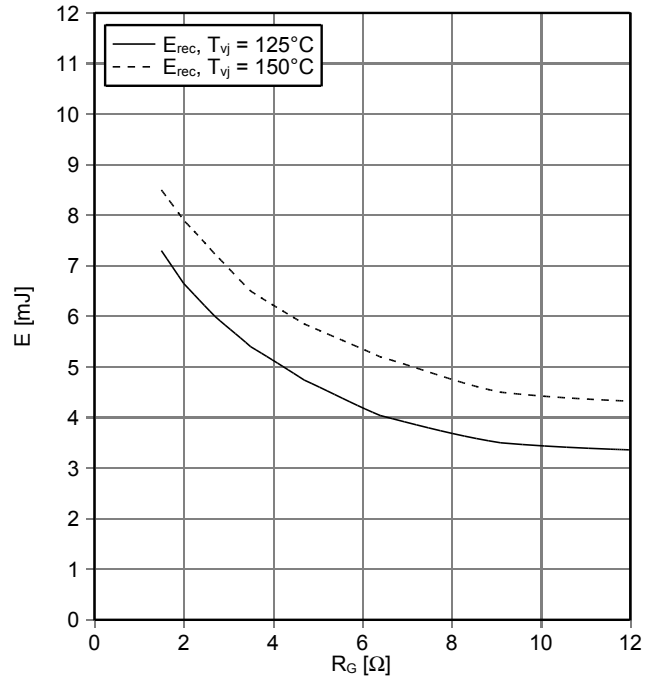
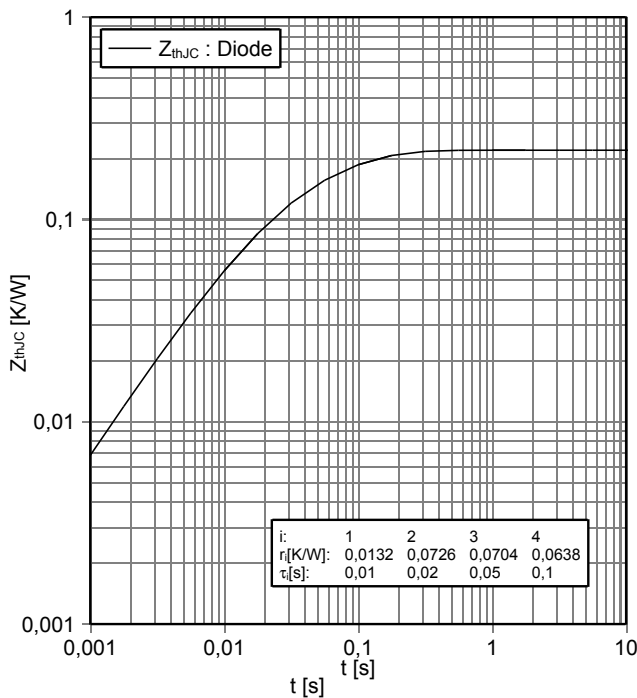


Fig.11 Transient thermal impedance Diode, Inverter

$Z_{thJC} = f(t)$



i:	1	2	3	4
r [K/W]:	0,0132	0,0726	0,0704	0,0638
τ [s]:	0,01	0,02	0,05	0,1

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